

Design Rules Manual RRAM_CMOS_DK

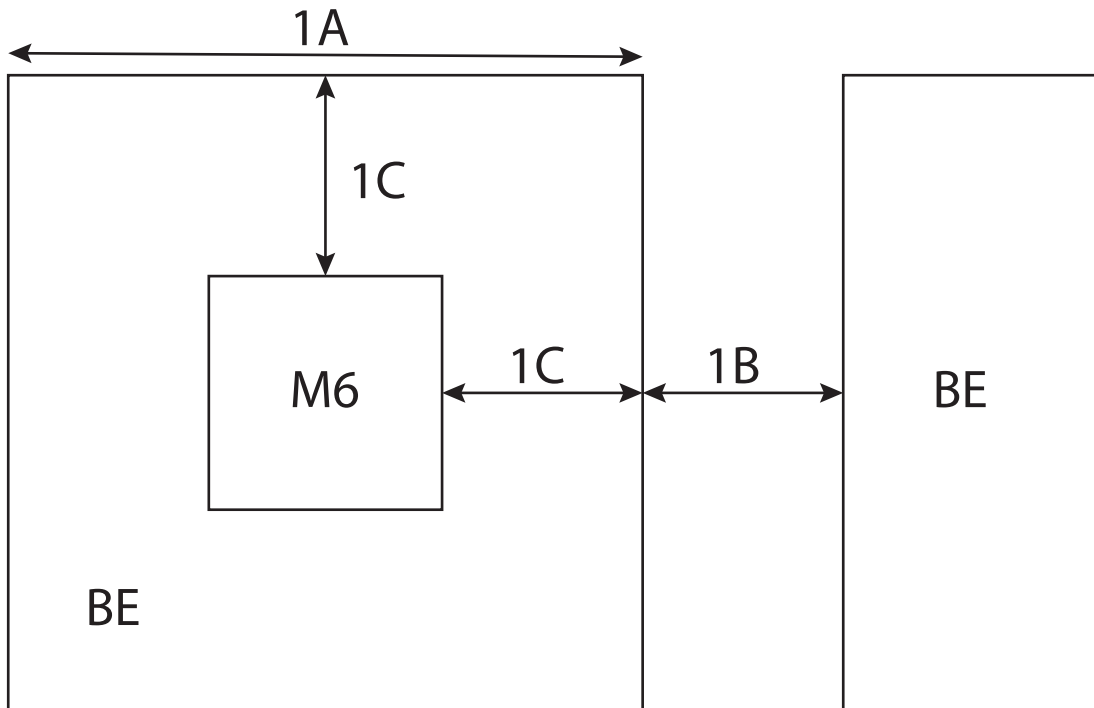
Version 1.1

Content

1.	Layer BottomElectrode	3
2.	Layer MetalOxide	4
3.	Layer TopElectrode.....	5

1. Layer BottomElectrode

	(unit : μm)
1A. Minimum BE width	1
1B. Minimum BE to BE	1
1C. Minimum BE layer enclosure of M6	1

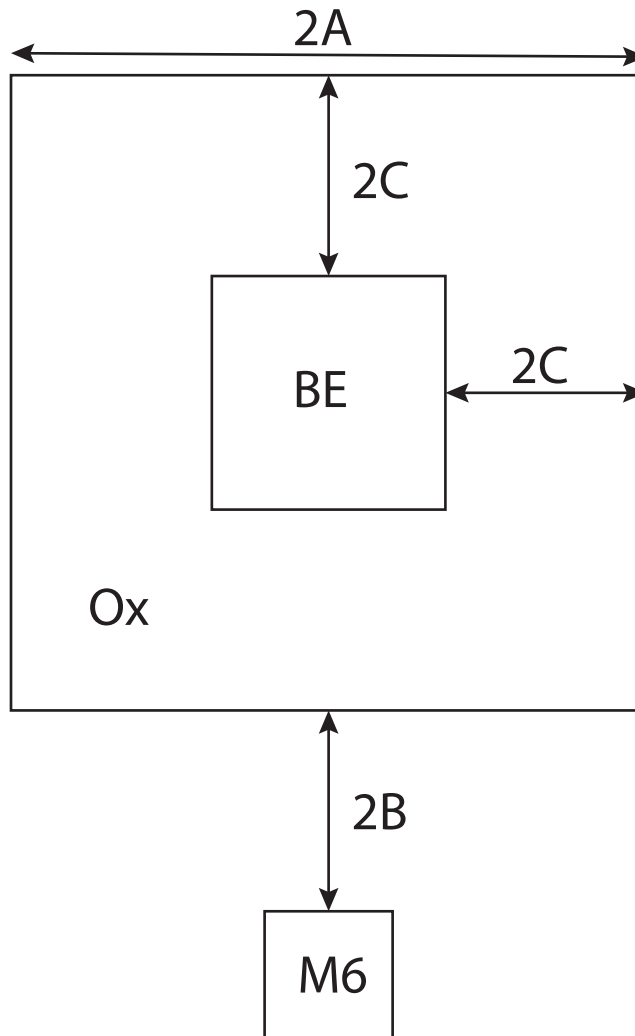


2. Layer MetalOxide

- 2A. Minimum Ox width
- 2B. Minimum Ox to M6
- 2C. Minimum Ox layer enclosure of BE

(unit : μm)

1
1
1



3. Layer TopElectrode

	(unit : μm)
3A. Minimum TE width	1
3B. Minimum TE to TE	1
3C. Minimum TE layer enclosure of Ox	1
3D. Minimum TE layer enclosure of M6	1
3E. Minimum TE to external M6	2

